



Material Content Data Sheet



Sales Product Name	TLE7239SL			Issued		28. August 2013		
MA#	MA000982078							
Package	PG-SSOP-24-5			Weight*		147.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.437	5.05	5.05	50489	50489
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		423	
	non noble metal	iron	7439-89-6	1.245	0.85		8454	
	non noble metal	copper	7440-50-8	50.568	34.33	35.23	343284	352267
wire	noble metal	gold	7440-57-5	0.408	0.28	0.28	2772	2772
encapsulation	organic material	carbon black	1333-86-4	0.166	0.11		1128	
	plastics	epoxy resin	-	7.644	5.19		51890	
	inorganic material	silicondioxide	60676-86-0	75.274	51.10	56.40	511002	564020
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11403	11403
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2480	2480
glue	plastics	acrylic resin	-	0.537	0.36		3645	
	noble metal	silver	7440-22-4	1.904	1.29	1.65	12924	16569
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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